

Title (en)  
HIGH IMPEDANCE SUBSTRATE

Title (de)  
SUBSTRAT MIT HOHER IMPEDANZ

Title (fr)  
SUBSTRAT HAUTE IMPEDANCE

Publication  
**EP 1661206 B1 20061213 (FR)**

Application  
**EP 04786396 A 20040830**

Priority  
• FR 2004050398 W 20040830  
• FR 0350492 A 20030902

Abstract (en)  
[origin: US2006044209A1] A high-impedance substrate including a first layer made of insulating material, having a lower face and an upper face, the substrate including conductor patterns mechanically linked to the substrate. Some of the conductor patterns mechanically linked to the substrate are associated with a magnetic tile. At least one electrical interconnection puts two points distinct from one another of a conductor pattern mechanically linked to the substrate in electrical contact, this conductor pattern having an assigned magnetic tile, passing above the magnetic tile associated with the conductor pattern mechanically linked to the substrate.

IPC 8 full level  
**H01Q 15/00** (2006.01); **H01Q 7/06** (2006.01)

CPC (source: EP US)  
**H01Q 7/06** (2013.01 - EP US); **H01Q 15/0066** (2013.01 - EP US)

Designated contracting state (EPC)  
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IT LI LU MC NL PL PT RO SE SI SK TR

DOCDB simple family (publication)  
**US 2006044209 A1 20060302; US 7071876 B2 20060704**; AT E348419 T1 20070115; CA 2508073 A1 20050317;  
DE 602004003717 D1 20070125; DE 602004003717 T2 20071018; EP 1661206 A1 20060531; EP 1661206 B1 20061213;  
FR 2859309 A1 20050304; FR 2859309 B1 20051216; JP 2007504643 A 20070301; JP 4901473 B2 20120321; NO 20053835 D0 20050815;  
WO 2005024999 A1 20050317

DOCDB simple family (application)  
**US 53847605 A 20050607**; AT 04786396 T 20040830; CA 2508073 A 20040830; DE 602004003717 T 20040830; EP 04786396 A 20040830;  
FR 0350492 A 20030902; FR 2004050398 W 20040830; JP 2006524404 A 20040830; NO 20053835 A 20050815